

ABSTRACT OF THE DISCLOSURE

A flip-chip bonding system. In flip chip bonding, a planar array of metallic pads is bonded to a mirror-image array by a film of solder between each pad-pair. Prior to bonding, testing may be done, by applying a mechanical probe to the pads, and reading, or applying, electrical signals. The probe may damage very small pads. Under the invention, small pads are configured in two parts, connected together. One part is used for probing, and the other is used to make the solder connection.